

DESCRIPTION

The MDL6050 is available in SOD-323 Package

FEATURES

- RoHS Compliant
- Available in SOD-323 Package

ORDERING INFORMATION

Package Type	Part Number			
SOD-323	MDL6050			
Note	3,000pcs/Reel			
AiT provides all RoHS Compliant Products				

PIN DESCRIPTION





ABSOLUTE MAXIMUM RATINGS

V _R , Reverse Voltage	70Vdc
I _F , Forward Current	200mAdc
I _{FM(surge)} , Peak Forward Surge Current	500mAdc

Stresses above may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated in the Electrical Characteristics are not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

THERMAL CHARACTERISTICS

Parameter	Symbol	Max.	Unit
Total Device Dissipation FR-5 Board ^{NOTE1}			
@ T _A = 25°C	P _D	200	mW
Derate above 25°C		1.57	mW/°C
Thermal Resistance Junction to Ambient	Reja	635	°C/W
Junction and Storage Temperature	T_{J}, T_{STG}	150	°C

NOTE1: FR-4 Minimum Pad

ELECTRICAL CHARACTERISTICS

T_A=25°C, unless otherwise noted

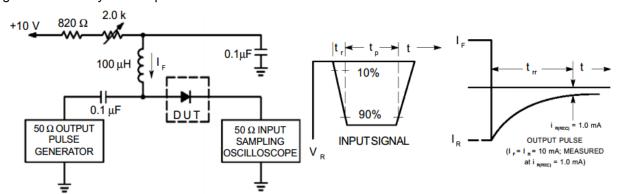
Parameter	Symbol	Conditions	Min	Tye	Max	Unit
OFF CHARACTERISTICS						
Reverse Breakdown Voltage	V _(BR)	I _{BR} =100μAdc	70			Vdc
Reverse Voltage Leakage Current	I _R	V _R =50Vdc			1.0	uAdc
Face of Welling	VF	I _F =1.0mAdc		0.55	0.7	Vdc
Forward Voltage		I _F =100mAdc		0.85	1.1	
Deverse Deservery Time	t _{rr}	I _F =I _R =10mAdc,			4.0	
Reverse Recovery Time		I _{R(REC)} =1.0mAdc(Figure1)			4.0 ns	
Capacitance	С	V _R =0V			2.5	pF

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TEST CIRCUIT

Figure 1. Recovery Time Equivalent Test Circuit



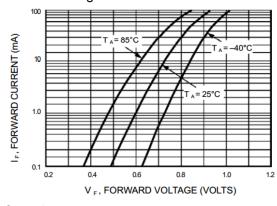
NOTE1: A $2.0k\Omega$ variable resistor adjusted for a Forward Current (I_F) of 10mA.

NOTE2: Input pulse is adjusted so $I_{R(peak)}$ is equal to 10mA.

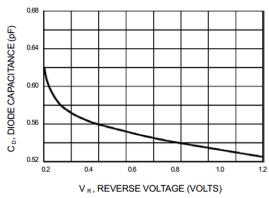
NOTE3: tp » trr

TYPICAL CHARACTERISTICS

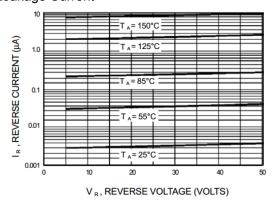
1. Forward Voltage



3. Capacitance



2. Leakage Current

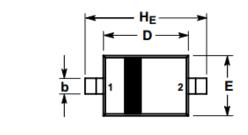


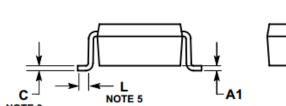
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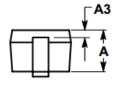


PACKAGE INFORMATION

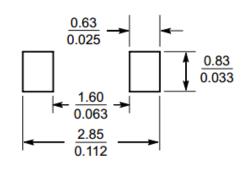
Dimension in SOD-323 Package (Unit: mm)







SOLDERING FOOTPRINT*



DIM	MILLIM	IETERS	INCHES		
	MIN	MAX	MIN	MAX	
Α	0.80	1.00	0.031	0.040	
A1	0.00	0.10	0.000	0.004	
A3	0.15 REF		0.006 REF		
b	0.25	0.40	0.010	0.016	
С	0.089	0.177	0.003	0.007	
D	1.60	1.80	0.062	0.070	
Е	1.15	1.35	0.045	0.053	
L	0.08		0.003		
HE	2.30	2.70	0.090	0.105	

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